

I. Listing of Claims

1. (Currently Amended) A microelectronic package comprising:

a housing including comprising an a cylindrical outer wall cylindrical about an axis and an inner wall defining a central compartment, said inner wall comprising having at least one assembly support surface that is parallel substantially faces [[to]] the axis, said housing further comprising including at least one axial channel interposed between the outer wall and the inner wall; and

a microelectronic assembly affixed to the assembly support surface.

2. (Original) The microelectronic package of claim 1 wherein the inner wall is non-concentric with the outer wall.

3. (Original) The microelectronic package of claim 1 wherein the support surface is planar.

4. (Currently Amended) The microelectronic package of claim 1 wherein the inner wall comprises first and second assembly support surfaces that are planar, and parallel to the axis, and wherein the microelectronic package comprises a first microelectronic assembly affixed to the first assembly support surface, a second microelectronic assembly affixed to the second assembly support surface, and a flexible interconnect connecting the first microelectronic assembly and the second microelectronic assembly.

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5. (Original) The microelectronic package of claim 1 wherein the channel is adapted for conveying cooling gas through the housing.

6. (Original) The microelectronic package of claim 1 wherein the housing comprises a first section having first axial edges and a second section having second axial edges joined to the first axial edges.

7. (Original) The microelectronic package of claim 6 wherein the first section comprises a semi-cylindrical wall and wherein the second section comprises a semi-cylindrical wall.

8. (Original) The microelectronic package of claim 1 wherein the housing is formed by a metal extrusion.

9. (Original) The microelectronic package of claim 1 wherein the housing is formed of a metal casting.

10. (Original) The microelectronic package of claim 1 wherein the housing is received in a tubular casing.

11. (Original) The microelectronic package of claim 1 wherein the support surface is a curve having a radius of curvature less than the radius of the outer wall.

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